

ABSTRACT OF THE DISCLOSURE

A chip cover with an insulative property and having a radiating portion has a housing portion on its lower surface. A flip chip piece, which has an electrode surface on which a plurality of projected electrodes of a semiconductor are arranged on its back surface, is accommodated in the housing portion. An anisotropic conductive adhesive agent is applied or printed to the electrode surface of the chip piece to embed the projected electrodes, and an insulative adhesive agent is applied or printed in a thicker configuration to a bonding surface which is provided on a lower surface of the chip cover and around the chip piece to embed the projected electrodes. The anisotropic conductive adhesive agent and the insulative adhesive agent are heat-pressed to be temporarily cured.